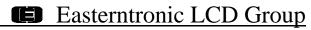
# **PRODUCT SPECIFICATION**

# CS2002C-D-YSNFDYN-122

V1.0

June 10, 2010





REV	Description	Date
V1.0	First Release	June 10, 2010

### **REVISION RECORD**

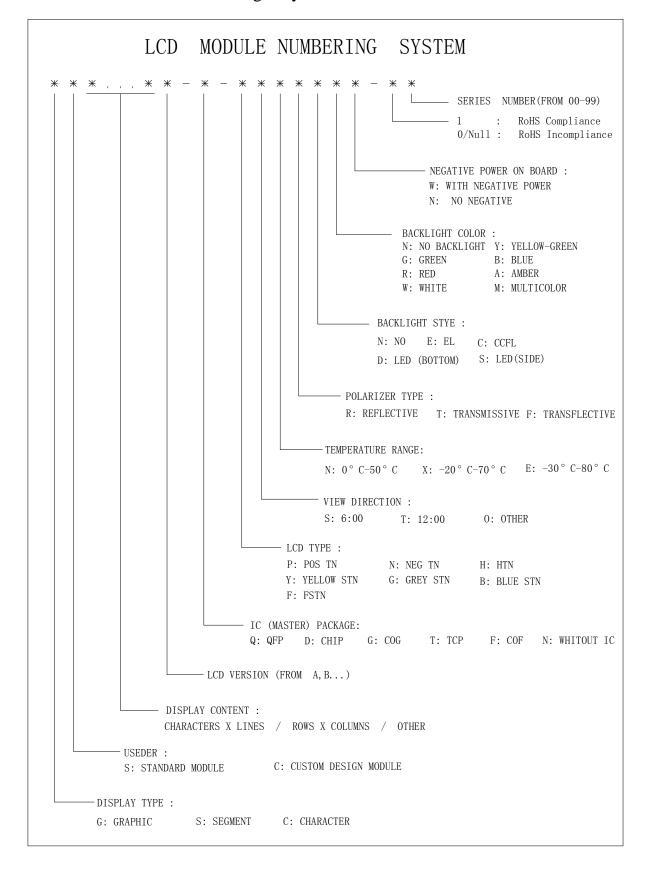


### CONTENTS

SE	CTIC	NS	DESCRI	PTION	PAGE NO.
1.	LC	D Module Nu	mbering	System	
2.	Тур	e Number Ar	nd Descr	iption	
3.	Me	chanical Spec	ifications		б
4.	Ele				7
	4.1				
	4.2				
_	4.3				
5.	Abs		-		
	5.1	Electrical Maxi	imum Rat	ings	
	5.2	Environmental	Condition	18 ·····	
6.	ELI	ECTRICAL SPE	ECIFICAT	IONS ···	
	6.1	Electrical Char	acteristics		
	6.2	Timing Specifi	cations		
7.	Pov	ver Supply For I	LCD Mod	ule	
8.	Ele	ctro-Optical Cha	aracteristic		
9.	Inst	ruction Table ····	••••••	•••••	
10.	Init	ialization By Ins	struction ··		
11.	Sof	tware Examples			
12.	Qua	ulity units			
13.	Chara	acterPattern			
14.	Pre	caution For Usir	ng LCM…	••••••	
15.	Dec	laration of conf	ormity reg	garding t	he limitation of
	dang	erous substance	s	•••••	



1. Type Number And Descr	ription
Type Number :	CS2002C-D-YSNFDYN-122
Description :	24 Characters X 2 Lines
LCD Panel :	Yellow-green STN, Transflective
Viewing angle :	6H
Duty :	1/16
Bias :	1/5
Operating Temperature:	$0^{\circ}C - 50^{\circ}C$
Storage Temperature :	$-10^{\circ}C - 60^{\circ}C$
Controller :	ST7066U-0T Or Equivalent
IC package :	Bonding
BackLight :	Yellow/Green LED, Bottom

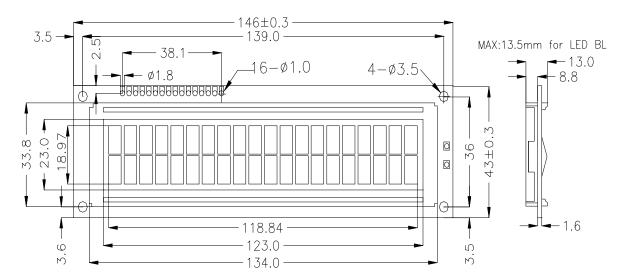


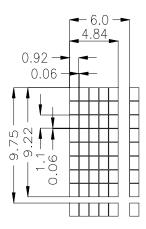
#### 2. LCD Module Numbering System



ITEM	STANDARD VALUE	UNIT
NUMBER OF CHARACTERS	20 CHARACTERS X 2 LINES	
CHARACTER FORMAT	5 X 8 DOTS	
MODULE DIMENSION	146.0(W) X 43.0(H) X13.0(T)	mm
EFFECTTVE DISPLAY AREA	123.0(W) X 23.0(H)	mm
CHARACTER SIZE	4.84(W) X 9.22(H)	mm
CHARACTER PITCH	6.0(W) X 9.75(H)	mm
DOT SIZE	0.92(W) X 1.1(H)	mm
DOT PITCH	0.98(W) X 1.16(H)	mm
APPROX WEIGHT	TBD	g
LCD TYPE	Yellow-green STN, TRANSFLEC	ΓIVE
DUTY AND BIAS	1/16 DUTY; 1/5 BIAS	
VIEWING DIRECTION	6:00	
BACK LIGHT	Yellow/Green LED, Bottom	

### 3. Mechanical Specifications





\*Remark : General tolerance refers this model. (±0.2mm)

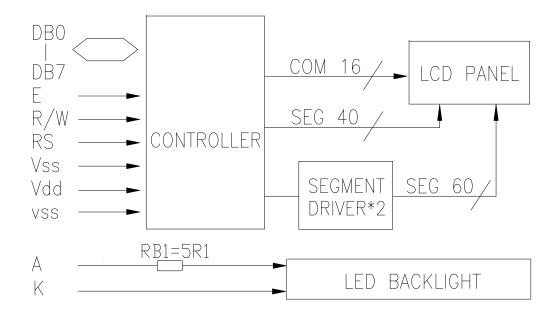
Easterntronic LCD Group

6

- 4. Electrical Block Diagram
  - 4.1 Pin Definition

PIN	SYMBOL	FUNCTION
1	Vss	Power Supply(GND)
2	Vdd	Power Supply(+5V)
3	Vo	Contrast Adjust
4	RS	Instruction/Data Register Select
5	R/W	Data Read/Write
6	Е	Enable Signal
7-14	DB0-DB7	Data Bus Line
15	А	Power Supply For LED BL(+)
16	Κ	Power Supply For LED BL(-)

4.2 Electrical Block Diagram



#### 4.3 Display Character Address Code

Display Position	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
Ddram	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	10	11	12	13
Address	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F	50	51	52	53



### 5. Absolute Maximum Ratings

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Supply Voltage (Logic)	Vdd – Vss	-	0	7.0	V
Supply Voltage (LCD Drive)	Vdd – V0	-	0	11.5	V
Input Voltage	Vi	-	-0.3	Vdd +0.3	V

#### Electrical Maximum Ratings(Ta=25deg C) 5.1

#### 5.2 **Environmental Conditions**

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Temp	Topr	Dry	0	50	deg C
Storage Temp	Ttsg	Dry	-10	60	deg C

### 6. ELECTRICAL SPECIFICATIONS

6.1 Electrical Ch	6.1 Electrical Characteristics at Ta=25 deg C, Vdd = $5V + / - 5\%$										
ITEM	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT					
Supply Voltage (logic)	Vdd-Vss	-	4.5	5	5.5	V					
Supply Voltage (LCD)	Vdd-V0	Vdd = 5V	4.4	4.7	5.0	V					
Input signal voltage	V-ih	"H" level	0.7Vdd	-	Vdd	V					
(for E, DB0-7,R/W,RS)	V-il	"L" level	0	-	0.6	V					
Supply Current (logic)	Icc	-	0.9	1	1.2	mA					
Supply Current (LCD)	lo	-	0.15	0.22	0.27	mA					
Supply Voltage (LED)	V-led	see note 1	3.9	4.1	4.3	V					
Supply Current (LED)	lf	see note 1	-	200	300	mA					
*Dook forward ourropt(D/L)	lfo	I mseo pulse			900	m (					
*Peak forward current(B/L)	lfp	10% Duty Cycle	-	-	900	mA					
*Power dissipation(B/L)	Pd		-	-	820	mW					

Note 1: LED backlight chips are arranged in two branches of 2 in series

\*For operation above  $25^{\circ}$ , the If, Ifp&Pd must be derated, the current derating is -7.2 mA/  $^\circ C$  for DC drive and -17.2 mA/ $^\circ C$  for pulse drive,the power dissipation is -29.52 mW / $^\circ C$ .The Blacklight working current must not more than 60% of the Ifmax or Ifpmax according to the working temperature



#### 6.2 Timing Specifications at Ta = 25 deg C, Vdd = 5V+/-10%, Vss =0V

### 6.2.1 Write mode

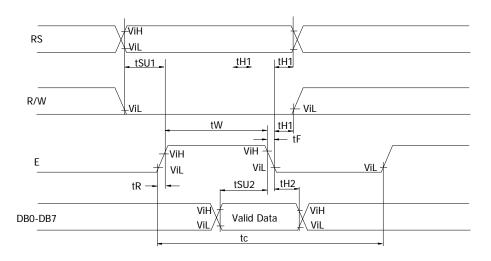
ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsul	0	-	ns
R/W and RS hold time	tH1	10	-	ns
Data set-up time	tsu2	40	-	ns
Data hold time	tH2	10	-	ns

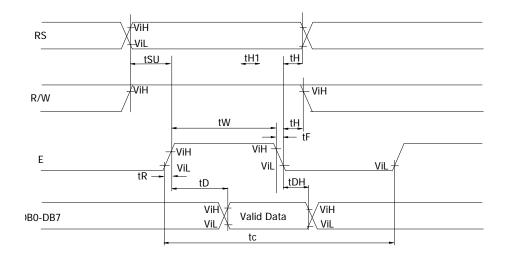
### 6.2.2 Read mode

ITEM	SYBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsu	0	-	ns
R/W and RS hold time	tH	10	-	ns
Data output delay	tD	-	120	ns
Data hold time	tDH	20	-	ns

### 6.2.3 Timing Diagram

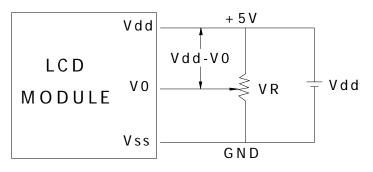
#### WRITE MODE TIMING DIAGRAM





#### READ MODE TIMING DIAGRAM

### 7. Power Supply For LCD Module



Vdd-V0: LCD Driving Voltage VR: 10K - 20K

#### 8. Electro-Optical Characteristic

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	REF.
Contrast	CR	<b>25</b> ℃		12			Note1
Rise Time	tr	<b>25</b> ℃		160	240	ms	Note2
Fall Time	tf	<b>25</b> ℃		100	150	ms	note 2
	θ 1- θ 2	<b>25</b> ℃			60	DEG	Note 3
Viewing Angle	Ø1, Ø2	250	-40		40	DEG	Note 5
Frame Frequency	Ff	<b>25</b> ℃		70		Hz	note 2

Note(1): Contrast ratio is defined under the following condition:

CR= brightness of non-selected condition

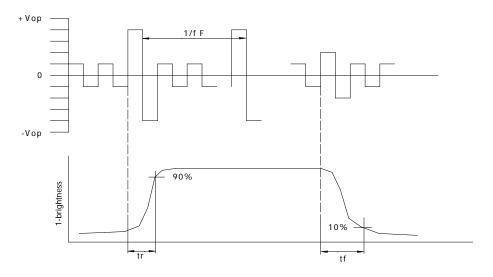
brightness of selected condition

(a). Temperature-----25C



- (b). Frame Frequency-----64Hz
- (c). Viewing angle-----  $\theta = 0, \ \emptyset = 0$
- (d). Operating Voltage---4.7V

Note(2): definition of response time:

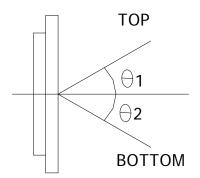


Condition:

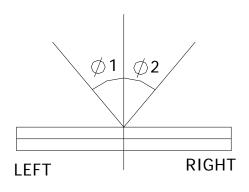
- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle----- $\theta = 0, \emptyset = 0$
- (d). Operating Voltage---4.7V

Note(3): definition of view angle:

**TOP-BOTTOM DIRECTION** 



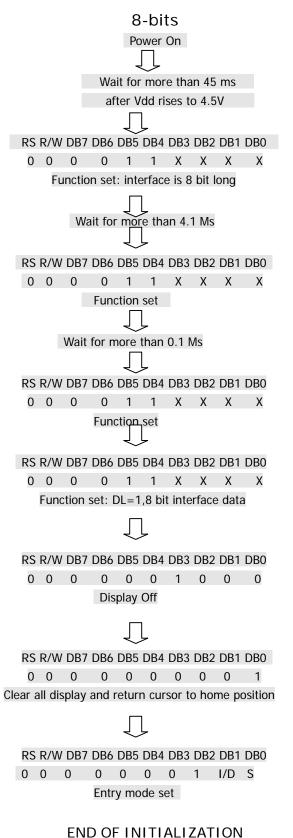
**RIGHT-LEFT DIRECTION** 



## 9. Instruction Table

Function	D	D									Description	Execu		
TUNCTION							В				•			
	3	vv										Time*		
<u> </u>	_	0		_	_	_	3	_		_		(Max)		
Clear	0	0	0	0	0	0	0	0	0		Clears entire display and returns the cursor to	1.64mS		
Display										-	home position (address 0)			
Return	0	0	0	0	0	0	0	0	1	Х	Return the cursor to the home position. DD RAM			
Home											contents remain unchanged. Set DD RAM address			
											to zero.			
Entry	0	0	0	0	0	0	0	1	1	S	Set cursor moving direction and enable the	40 µ S		
mode									/		shift of the display. These operations are			
set									D		performed during data write/read of DD RAM/CG			
											RAM. 1/D=1: increment; 1/D=0: decrement; S=1:			
											whole display shift when data is written.			
Display	0	0	0	0	0	0	1	D	С	В	Set display (D),cursor(C) and blinking of cursor(B)	40 µ S		
ON/OFF											ON/OFF. D=1:display ON; D=0: display OFF.			
control											C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON;			
											B=0, Blink OFF.			
Cursor or	0	0	0	0	0	1	S	R	Х	Х	Move the cursor and shift the display without	40 µ S		
Display		-	-		-		1	1			changing DDRAM contents. S/C=1: Display Shift;			
shift							Ċ	Ì			S/C=0:Cursor move. R/L=1:shift to right;			
								-			R/L=0:shift to left.			
Function	0	0	0	0	1	D	N	F	х	х	Set interface data length (DL), number of display	40 µ S		
Set	ľ	Ŭ	Ĭ	Ŭ				•	<sup>^</sup>	<sup>^</sup>	lines (N) and character font (F).DL=1: 8 bits;			
501											DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1:			
											5X11  dots; F=0: 5X7  dots.			
Set CG	0	0	0	1			A	2			Set CG RAM address. CG RAM data is sent and	40 u S		
RAM add	0	0	0	1			Α	.6	J			40 µ 3		
	_	0	1			٨		<u> </u>			received after this setting.	10 11 5		
	0	U	ľ			А	D	υ			Set DD RAM address. DD RAM data is sent and	40 µ 3		
RAM Add		4	_								received after this setting.	0 0		
Read BF	0	1				4	AC	,			Read BUSY FLAG (BF) and the contents of the			
& Addr			F								address counter. BF=1: internal operation; BF=0:			
											can accept instruction.			
Write Data	1	0	١	N	SI.	TE	E	CAC	TA	ł	Write data into DD RAM or CG RAM.	40		
to RAM												μ <b>S**</b>		
Read Data	1	0		RI	EA	D	D	A	ΓA		Read data from DD RAM or CG RAM.	40		
from RAM												μ <b>S**</b>		

### **10.Initialization By Instruction**



4-bits Power On Wait for more than 45 mS after Vdd rises to 4.5V RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 1 Function set: DL=1,8 bit interface data. Wait for more than 4.1 Ms RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 1 DL=1,8 bit interface data Wait for more than 0.1 Ms RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 0 DL=0,4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 0 0 0 N F X X Function set: DL=0,4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 1 0 0 0 Display Off ٦Ļ RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 0 0 0 1 Function set: DL=0.4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 0 1 I/D S Entry mode set END OF INITIALIZATION

## 11.Software Examples

#### 8-BIT OPERATION 8 characters X 2 lines

	ION			rac							
Function	RS R	W D7	D6	D5	D4	D3	D2	D1	D0	DISPLAY	DESCRIPTION
Power on delay											Initialization. No display appears.
Function set	0 0	0	0	1	1	0	0	Х	Х		Sets 8-bit operation, 2-line display and 5*7
											dots character font.
Display OFF	0 0	0	0	0	0	1	0	0	0		Turn off display.
Display ON	0 0	0	0	0	0	1	1	1	0		Turn on display and cursor.
Entry Mode set	0 0	0	0	0	0	0	1	1	0		Set mode to increment the address by one
										·	and to shift the cursor to the right, at the
											time of write to the DD/CG RAM. Display
											is not shifted.
Write data to	1 0	0	1	0	0	1	1	1	1	0	Write "O". Cursor incremented by one and
CG/DD RAM											shift to right.
Write data to	1 0	0	1	0	1	0	0	1	0	OR	Write "R". Cursor incremented by one and
CG/DD RAM											shift to right
Write data to						•				ORIENT	Write "I" "E" "N" "T".
CG/DD RAM											
Set DDRAM	0 0	1	1	0	0	0	0	0	0	ORIENT	Set RAM address so that the cursor is
address											positioned at the head of the Second line
Write data to						•				ORIENT	Write "D" "S".
CG/DD RAM										DS	
Cursor or display	0 0	0	0	0	1	0	0	Х	Х	ORIENT	Shift only the cursor position to the left.
shift										DS	
Write data to										ORIENT	Write "I" "S" "P" "L" "A" "Y"
CG/DD RAM										DISPLAY	

### 4-bit operation (4-bits 1 line)

Function	RS	RW	' D7	D6	D5	D4	Display	Description	
power on delay								Initialization. No display appears.	
Frnction set	0	0	0	0	1	0		Sets to 4-bit operation. In this case, operation is handled as 8-bits by initialization, and Only this instruction completes with one write.	
Frnction set	0 0	0 0	0 0	0 0	1 X	-		Sets 4 -bit operation, 1-line display and 5*7 dot character font. (number of display lines and character fontscannot b changed hence after.)	
Display ON/OFF Control		0 0	0 1	0 1	0 1		_	Turn on display and cursor.	
Entry Mode Set		0 0	0 0	0 1	0 1		_	Turn on display and cursor.	
Write data to CG/DD/ARM		0 0	0 1	1 1	0 1	0 1		Write "O". Curaor incrementer by one and shift to right.	
	same as 8-bit operation								

### 12. Quality units

### 12.1 Purpose

This standard for quality assurance should define the quality of LCD module products to customer by EASTERNTIONIC LCD GROUP.

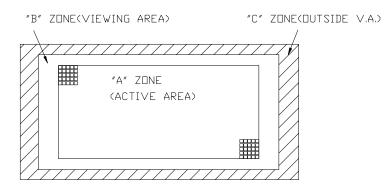
12.2 Scope

This document defines general provisions as well as inspection standards for LCD module supplied by EASTERNTIONIC LCD GROUP, except for those with special requirements from customer.

### 12.3 Definition

### 12.3.1 Definition of area

- A Zone: Active area.
- B Zone: Viewing area
- C Zone: Outside viewing area.



### 12.3.2 Definition of size

Large size(L):  $1 \sim 6 \text{ pcs LCD}$  screens are cut out of from each  $14" \times 16"$  mother glass. Middle size(M):  $7 \sim 50$  pcs LCD screens are cut out of from each  $14" \times 16"$ mother glass. Small size(S): more than 50 pcs LCD screens are cut out of from each  $14"\times16"$ mother glass.

12.4 Quality Specification

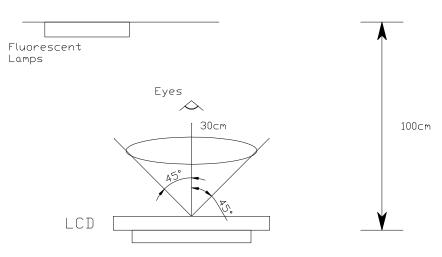
### 12.4.1 Conditions of Cosmetic Inspection

12.4.1 Test should be conducted under the following conditions:

Ambient temperature :22 $\pm$ 5°C. Ambient humidity:  $65 \pm 20\%$ RH Ambient Luminance: 40-watt fluorescent lamp. An appearance test should be conducted by human sight at approximately 30 cm distance



from the LCD module under fluorescent light. Distance between LCD and fluorescent lamps should be 100 cm or more. Viewing direction for inspection is 45° from vertical against LCD.



12.4.1.2 When test the model of transmissive product must add the reflective plate.

### 12.4.2 Sampling plan

Unless otherwise agreed in writing, the sampling inspection shall be applied to the incoming inspection of customer.

- Lot size: Quantity of shipment lot per model
- Sampling type: Normal inspection, single sampling
- Sampling Level: Level II
- Sampling table: GB/T2828.1.1(GB-national standard of China)

12.4.3 Classification of defects and Acceptable quality level

Defects and classified as either a major or minor defect defined as bellows:

- Major defect: It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.

- Minor defect: It is a defect that will not result in functioning problem with deviation calssifiec.

The AQL for major and minor defects is defined as follows:

Partition	Definition	AQL
Major defect	Functional defective as product	0.4
Minor defect	Satisfy all functions as product but not satisfy cosmetic standard	1.0

12.4.4 Applicable instrument



- LCD module tester
- Multimeter
- Caliper
- Defect size filming standard

### 12.4.5 Inspection quality criterion

### 12.4.5.1 LCD panel part

Classify	Item	Description of defects	Inspectio	on criterion	Drawing specification
Major defect	1.Non-display	Product no function	Not accept		
	2.LCD with wrong view direction`	Difference in Spec.	Not	accept	
	3.Segment missing	Part or all pattern do not light up	Not	accept	
	4.Occur high current	Current exceed designed value	Not	accept	
	5. LC leakage	LC does not fulfill the glass cell	Not accept		
	6.Deviation from drawing	LCM Dimension difference from drawing and over tolerance	According to dimensions noted in the specification		
	7.Wrong type applied	Wrong polarizer attachment	Not	accept	
		Pin attached wrong type applied	Not	accept	
	8.Incorrect pins quality	Pin attached wrong quantity applied	Not accept		
Minor defect	9.Pattern deformation	Segment fatter or smaller	Dimension (mm) A≤0.1	Acceptable number Not count (Should not be connected to next dot)	



Minor	10 Pinholos	Plack anot/white	$B \le 0.10 \qquad \text{Not count}$	or
Minor defect	10.Pinholes	Black spot/white spot at activated state	1. large size LCD Accept if can't be found at Im distance and will not enlarge under electronic tes 2. Middle size LCD Diameter(mm) Accept QTY $\Phi \le 0.15$ Not count $0.15 < \Phi \le 0.25$ 3 $0.25 < \Phi \le 0.35$ 1 $\Phi > 0.35$ 0 3. Small size LCD Diameter(mm) Accept QTY $\Phi \le 0.15$ Not count $0.15 < \Phi \le 0.25$ 2 $0.25 < \Phi \le 0.30$ 1 $\Phi > 0.30$ 0 4. For the dot pattern accept if the area of defect is less than of equal to half of on lattice's 5. Only allow one defect if one segment 6. The nearest diatance allowed between tw pinholes is 20mm	At $\Phi = (X+Y)/2$ $\Phi = (X+Y)/2$
	11.Blemishes and foreign matters	Black spot/dust on LCD(non-display )	Positive panel: 1.A zone - Large size LCD Accept if can't find at 1n distance and will not enlarg under electronic test:	



-Middle size LCD	
Diameter(mm) Accept QTY	
$\Phi \leq$ 0.15 Not count	
$0.15 < \Phi \le 0.25$ 3	
$0.25 < \Phi \le 0.35$ 1	
$\Phi \! > \! 0.35$ 0	
-Small size LCD	
Diameter(mm) Accept QTY	
$\Phi \leq$ 0.15 Not count	
$0.15 < \Phi \le 0.25$ 2	
$0.25 < \Phi \le 0.30$ 1	
$\Phi \! > \! 0.30$ 0	
2.B zone	
1.5 times of acceptable	
largest diameter size of Zone	
A	
3.C zone	
Notcount.	
Negative panel:	
1. A zone	
-Large size LCD	
Diameter(mm) Accept QTY	
$\Phi \leq$ 0.15 Not count	
$0.15 < \Phi \le 0.30$ 4	
$0.30 < \Phi \le 0.50$ 1	
$\Phi \! > \! 0.50$ 0	
-Middle&small size LCD	
Diameter(mm) Accept QTY	
$\Phi \leq$ 0.15 Not count	
$0.15 < \Phi \le 0.25$ 3	
$\Phi \! > \! 0.25$ 0	
2. B zone	
1.5 times of acceptable	
largest diameter size of Zone	
A	
3.C zone	
No count	
The nearest diatance allowed	
between two black spot is	
20mm	

12.Black	Scratch on glass	Positive panel:	
lines and	or polarizer	1.A zone	1
scratches	surface.And		
scratches		- Large size LCD	
	foreign linear	Accept if can't find at 1m	
	matters in LCD	distance and will not enlarge	
		under electronic test.	
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02{<}W{\le}0.03{,}L{\le}4$ 2	
		$0.03 {<}~W {\leq}~0.05, {L} {\leq}3 {\qquad} 2$	
		$0.02 < W \le 0.03$ ,L >4 0	
		$0.03 < W \le 0.05, L > 3 = 0$	
		W>0.05 As the spot criteria.	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 2$ 1	
		$0.02 < W \le 0.03, L > 4$ 0	
		$0.03 < W \le 0.05, L > 2$ 0	
		W > 0.05 As the spot criteria.	
		2.B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		Notcount.	
		Negative panel:	
		1. A zone	
		-Large size LCD	
		Diameter(mm) Accept QTY	
		W≤0.02 Not count	
		$0.02 < W \le 0.03, L \le 5$ 3	
		$0.03 < W \le 0.05, L \le 4$ 2	
		$0.02 < W \le 0.03, L > 5$ 0	
		$0.02 < W \le 0.05, L > 3$ 0 $0.03 < W \le 0.05, L > 4$ 0	
		W > 0.05 As the spot criteria.	
		i i vite internetine spot enternet.	
		-Middle size LCD	
	1	-	



			Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 4$ 2 $0.03 < W \le 0.05, L \le 2$ 2 $0.02 < W \le 0.03, L > 3$ 0 $0.03 < W \le 0.05, L > 2$ 0 W > 0.05 As the spot criteria. -Small size LCD Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 3$ 2 $0.03 < W \le 0.05, L \le 3$ 1 $0.02 < W \le 0.03, L > 3$ 0 $0.03 < W \le 0.05, L > 2$ 0 W > 0.05 As the spot criteria. <b>2. B zone</b> 1.5 times of acceptable largest diameter size of Zone A <b>3.C zone</b> Not count The nearest diatance allowed between two defects is 20mm	
Mintor defect	13. Scratch on PI coating	PI coating scratched	The visible scratch of A zone can not be accepted at 30cm view	
Mintor defect	14. Rainbow	Arches,circular or parallel colorful spread	distance. According to the limit specimen	
Mintor defect	15. Bubbles or wrinkles in polarizer	Bubbles or wrinkles between polarizer and glass	A zone:The visible defect can not be accepted at 30cm view distance. B zone: Not count	
Mintor defect	16. Position of polarzer attachment	Wrong polarizer attachment in position or dimension	Polarizer protruding from edge of glass and exceeding/within the maximum external dimension of LCD	



		ſ	1				
Mintor	17. Ink	17.1 Ink	Not acce	pt			
defect	printing	line/pattern					
	defect	broken					
		17.2 Ink	Accept i	f the thick	c or thir	part is	
		pattern/line	-	n equal to		-	
		jagged		r accordi		-	
		J#880#	specimer				
		17.3 Light	*	activated	with	current	
		leakage		ht appears			
		Тсакаде		ble or scra			
			-				
				misalignr		-	
			to the pli	nhole spec	11101	1.	
		17.4 Ink printing	Reject if	the thick	or thin	in more	
		pattern/line	than $1/2^{V}$		or thin		
		uneven		hen W1-V	V2<1/3	V	
		uneven	Reject w		1221/31	•	
Mintor	18. Pin defect	18.1 Corrosion	Pin	incomin	g	defect:	`
defect		or foreign		,damage(i	0		
		material on		damaged)			
		terminal legs		om glass			
			legs.Not	-	, ,, ,, ,,	•••••	
		18.2 Pin		ng to the s	necifica	tion	
		deviation over	7 iccordin		peemea	tion	
Mintor	10 Chinned	tolerance 19.1 Chip in	2	b	C	accent	
defect	19. Chipped	-	а	U	с	accept QTY	
defect	glass on	lead contact		1. au		QII	
	comer	area.	a≤5mm	b≤W	c≤T	2	
			L>5m			3	ITD
			m				
			a <l< td=""><td>b≤W</td><td>c≤T</td><td>3</td><td></td></l<>	b≤W	c≤T	3	
			L<5m				b c ~ ~ ~ ~
			m				
		19.2 Others	Not ev				× ~
		17.2 Oulers	width of		c≤T	3	
			width Of	scal	U>1	5	



Mintor defect	20. Glass	а	b	c	accept QTY	A A A		
		a≤5mm	Not exceed 1/2 width of seal	c≤T	3			
Mintor	21. Clipped electrode pad	21.1Glass chip on ITO edge	a	b	c	accept QTY	ITD	
defect	-		a≤4mm (and not exceed 4 ITO termina 1	b≤W/4	c≤T	3		
		21.2 Glass chip on ITO back	a	b	c	accept QTY		
			a≤5mm	b≤W/3	c≤T	3		
Mintor defect	22. Mechanical	Extended crack inspector shall	b	acce		QTY		
	damage	attempt to remove the chip with tweezers,re-eval uate if the	b≤W/4		2			
		remaining defect is still a crack or a chip						
Mintor defect	23.Gla	Not acce	pt					
defect Q	nimum space be TY in total:	tween any 2 defec ≤ 5/unit, Zone B≤ 5		t) should	more	than 20m	m, and max. allowed	

Middle size LCD: Zone A $\leq$  3/unit, Zone B $\leq$  3/unit;

Small size LCD: Zone A $\leq$  2/unit, Zone B $\leq$  2/unit;



## 12.4.5.2 Other part

NO.	Items	Criterion of defects	AQL				
1	Backlight	<ol> <li>Lumination source flickers.</li> <li>Using spot, lines and contamination standard of LCD to judge the spots or scratches defect on backlight.</li> </ol>					
		3. Not allow unlighted on backlight.	Major				
		4. Colour and luminance of backlight should correspond its specification.	Major				
2	PCB,COB	1.COB seal may not have pinholes larger than0.2mm or contamination.					
		2.COB seal surface may not have pinholes through to the IC.	Minor				
		3. The height of COB should not exceed the height indicated in the assembly diagram.	Major				
		4. Beyond 2mm of the seal area, there may not have sealant on the PCB.	Minor				
		5.No oxidation or contamination on PCB connector.	Minor				
		6.Parts on PCB should correspond the characteristic, and not	Major				
		allow wrong parts, missing parts or additional parts.					
		7.The jumper on the PCB should correspond to the characteristic.	Minor				
		8. The solder which gets on bezel, LED pad, zebra pad or screw hole pad should be smoothed down.	Major				
		1. No unmelted solder pastes on the PCB.	Minor				
3	Soldering	2. No cold solder joints, solder connection missing, oxidation of solder.	Minor				
		3. No short circuits in components on PCB.	Minor				
4	General Appearance	1. No oxidation, contamination, curves, cracks or bends on interface Pin of TCP.	Minor				
		2. No solder residue or solder balls on product.	Minor				
		3. The IC on TCP may not be damaged.	Major				
		4. The residual rosin or tin oil of soldering(component or chip component) is not turned into brown or black colour.	Minor				
		5. Packing method correspond the specification.	Major				
		6. Dimension and structure correspond the specification sheet.	Major				
		7. No dirt and break on the heat seal.	Major				

## 12.5 Reliability

Item	Condition							
High temperature operation	$+50^{\circ}\text{C}\pm2^{\circ}\text{C}$ , 8 ho							
Low temperature operation	$0^{\circ}C \pm 2^{\circ}C$ , 8 hour	1.Total current consumption						
Humidity	Operation	40 °C $\pm$ 2 °C ,93% $\pm$ 2% RH,8 hours	should be below double of initial					
	Storage	40 °C ± 2 °C ,93% ± 2%RH, 24 hours	value. 2.Cosmetic defects					
High temperature storage	$+60^{\circ}C \pm 2^{\circ}C$ , 10 h	should not be happened						
Low temperature storage	-10℃±2℃, 10h							
Thermal shock								
storage	60min~60min, 5 cy							
Vibration test	Amplitude:0.7~1.0							
	in each direction(X							
Shock test	To be measured aft							
	U U	oncrete surface in packing						
	state.(weight≥15K Weight<15Kg,dro							
Domoriu Tho fun		Dropping method corner dropping A corner: once Edge dropping B,C,D edge: once Face dropping E,F,G face: once	reco. of the normal					
		conducted after 4 hours sto	rage at the normal					
temperature and hu	imidity after remove	d from the test chamber.						

The LCD module shall not fail the following reliability test.

### 13. Character Pattern

67-64 63-60	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM (1)															
0001	(2)															
0010	(3)															
0011	(4)															
0100	(5)															
0101	(6)															
0110	0															
0111	(8)															
1000	(1)															
1001	(2)															
1010	(3)															
1011	(4)															
1100	(5)															
1101	(6)															
1110	(7)															
1111	(8)															



#### 14.Precaution For Using LCM

#### 1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The followina precautions should be taken when handing,

(1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.

(2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface. Wipe gently with cotton. Chamois or other soft material soaked in petroleum benzin.

Wipe off saliva or water drops immediately. (3). Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.

(4). Glass can be easily chipped or cracked from rough handing. especially at corners and edges.

(5). Do not drive LCD with DC voltage.

2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

(1). Do not tamper in any way with the tabs on the tabs on the metal frame.

(2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattem.

(3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).

(4). When mounting a LCM make sure that the PCB is not under any tress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.

(5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing piels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

(1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

(2). The modules should be kept in antistatic bags or other containers resistant to static for storage.

(3). Only properly grounded soldering irons should be used.

(4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.

(5). The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.

(6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.

2.3. Soldering

(1). Solder only to the I/O terminals.

(2). Use only soldering irons with proper grounding and no leakage.

(3). Soldering temperature: 280  $^{\circ}C \pm 10^{\circ}C$ 

(4). Soldering time: 3 to 4 sec.

(5). Use eutectic solder with resin flux fill.

(6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.

2.4. Operation

(1). The viewing angle can be adjusted by varying the LCD driving voltage V0.

(2). Driving voltage should be kept within specified range; excess voltage shortens display life.

Response time increases with decrease in (3). temperature.

(4). Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".

(5). Mechanical disturbance during operation (such as pressing on the viewing area) nay cause the segments to appear "fractured".

2.5. Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

2.6. Limited Warranty

Unless otherwise agreed between EASTERNTRONIC and customer, EASTERNTRONIC will replace or repair any of its LCD and LC, which is found to be defective electrically and visually when inspected in accordance with EASTERNTRONIC acceptance standards, for a period on one year fron data of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of EASTERNTRONIC is limited to repair and/or replacement on the terms set forth above. EASTERNTRONIC will not responsible for any subsequent or consequential events.

15. Declaration of conformity regarding the limitation of dangerous substances

## 深圳易事通液晶显示模块有限公司

SHENZHEN EASTERNTRONIC LCM CO., LTD.

4F, B3 Building, FuYuan Industrial Zone, FuYong Town,

BaoAn District, ShenZhen, P.R.China

DECLARATION OF CONFORMITY REGARDING THE LIMITATION OF DANGEROUS SUBSTANCES

WE, SHENZHEN EASTERNTRONIC LCM CO., LTD,

Declare that the product of CS2002C-D-YSNFDYN-122 complies with: The directive 2002/95/EC Dated 2003/01/27 regarding the limitation of dangerous substances, in particular to clause 4 which forbids the use of the following elements:

•Lead

Mercury

● Cadmium

•Hexavalant chromium

Polybrominated biphenyls

• Polybrominated diphenylethers

And to the annex which points out the exempted implementations  $\Box$  To the directive 73/23/eec dated 1973/02/19 and the standard EN60335-1 regarding prohibition of following elements:

• 0ils containing polychlorinated biphenyl

Asbestos

• Radioactive substances

SHENZHEN EASTERNTRONIC LCM CO ., LTD.

Issued on June 10, 2010

According with the proposal of Technical Adaption Committee (TAC) of a limit of 0.1% by weight for lead hexavalent chromium, mercury, PBBs and PBDRs and 0.01% by weight for Cadmium.

